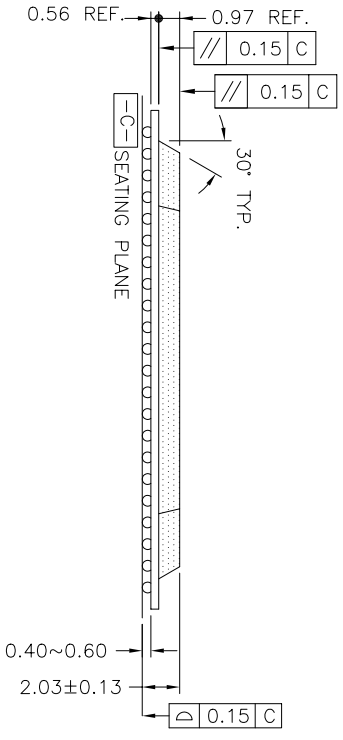
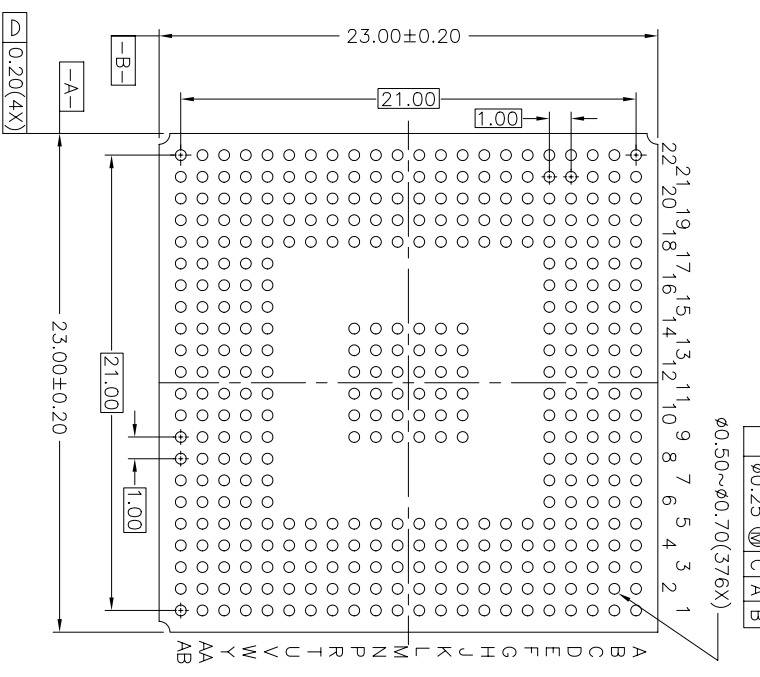
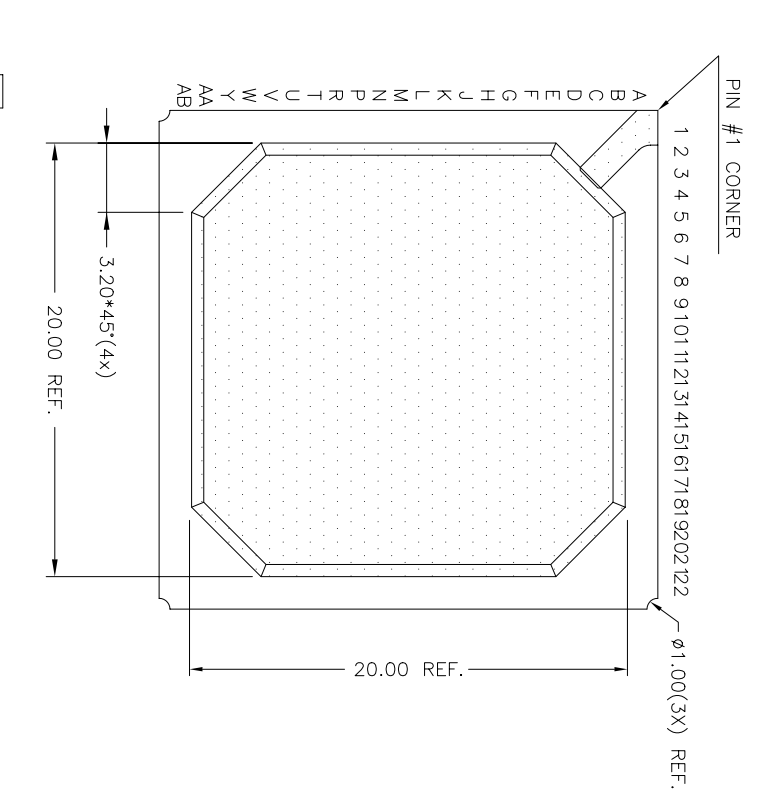



REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
00		INITIAL RELEASE	07/08/09	P.PAIK



Ball Pitch :	1.0	Substrate Thickness :	0.56
Ball Diameter :	0.6	Mold Thickness :	0.97

TOLERANCES UNLESS SPECIFIED	ANGULAR ±1°	 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com
DECIMAL XX±.05		
XXX±.030		
APPROVALS	DATE	
DRAWN <i>QAC</i>	7/7/09	TITLE AM/AMG 376 PACKAGE OUTLINE
CHECKED		23 x 23 mm BODY
		1.00 mm PITCH PBGA

SIZE	DRAWING No.	REV
C	PSC-4269	00
DO NOT SCALE DRAWING		
		SHEET 1 OF 1